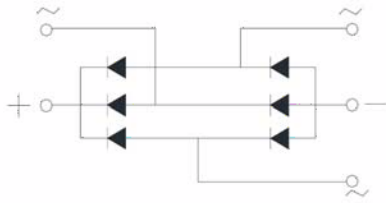




UL recognition, file #E230084
 Low thermal resistance
 Glass passivated chip junction
 High surge current capability
 Solder dip 275 °C max. 7 s, per JESD 22-B106

: Tin plated leads, solderable per
 J-STD-002 and JESD22-B102
 As marked on body



($T_a=25$ Unless otherwise specified)

| Device marking code | | | | SKBPC2504 | SKBPC2506 | SKBPC2508 | SKBPC2510 | SKBPC2512 | SKBPC2514 | SKBPC2516 |
|--|------------------------------|-----------|--------|------------|-----------|-----------|-----------|-----------|-----------|-----------|
| Maximum Repetitive Peak Reverse Voltage | | VRRM | V | 400 | 600 | 800 | 1000 | 1200 | 1400 | 1600 |
| Maximum RMS Voltage | | VRMS | V | 280 | 420 | 560 | 700 | 840 | 980 | 1120 |
| Maximum DC blocking Voltage | | VDC | V | 400 | 600 | 800 | 1000 | 1200 | 1400 | 1600 |
| Average rectified output current @60Hz sine wave, R-load | With heatsink $T_c = 110$ | IO | A | 25 | | | | | | |
| Forward Surge Current (Non-repetitive) @8.3ms Half-sine wave, 1 cycle, $T_j=25$ | | IFSM | A | 360 | | | | | | |
| Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, $T_j=25$ | | | | 720 | | | | | | |
| Current squared time @1ms t 8.3ms $T_j=25$, Rating of per diode | | I^2t | A^2s | 538 | | | | | | |
| Storage temperature | | T_{stg} | | -55 ~ +150 | | | | | | |
| Junction temperature | | T_j | | -55 ~ +150 | | | | | | |
| Dielectric strength @ Terminals to case, AC 1 minute | | Vdis | KV | 2.5 | | | | | | |
| Mounting torque @ Recommend torque 5kg cm | | Tor | kg cm | 8 | | | | | | |



$T_a=25$ Unless otherwise specified

| | | | | |
|---|----|---------|---|-----|
| Maximum instantaneous forward voltage drop per diode | VF | V | $I_{FM}=12.5A$ | 1.1 |
| Maximum DC reverse current at rated DC blocking voltage per diode | IR | μA | $T_j=25$ | 5 |
| | | | $T_j=125$ | 500 |
| Typical junction capacitance | Cj | μF | Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C | 175 |
| | | | | 145 |

$T_a=25$ Unless otherwise specified

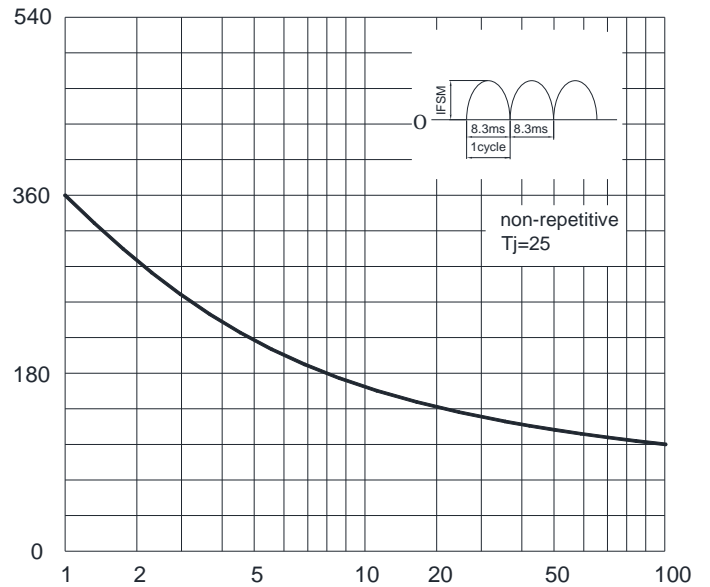
| | | | | |
|----------------------------|--|-------|----|-----|
| Typical Thermal Resistance | Between junction and case, With heatsink | R J-C | /W | 1.5 |
|----------------------------|--|-------|----|-----|

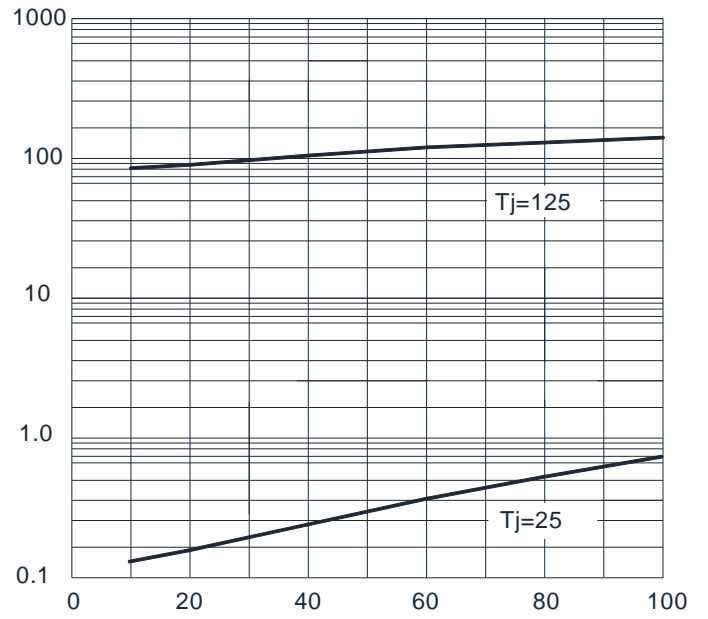
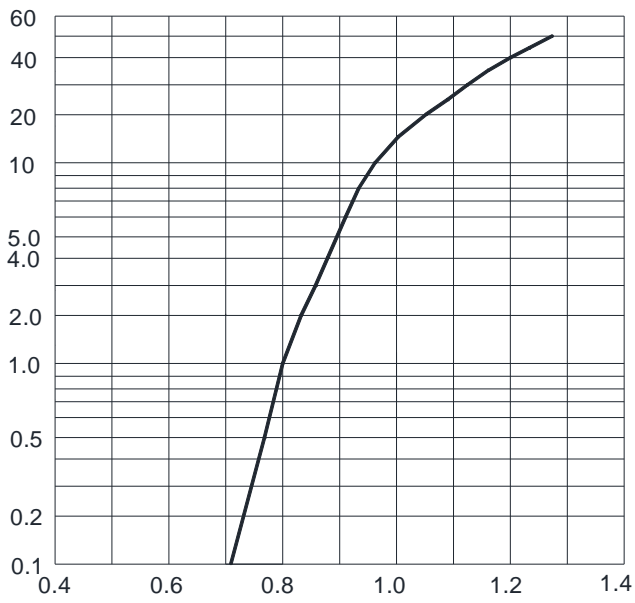
Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

(Example)

| | | | | | | |
|--|----|----------------|----|----|-----|-----------|
| | A1 | Approximate 19 | 50 | 50 | 500 | Paper Box |
|--|----|----------------|----|----|-----|-----------|

(Typical)





| A | 23.1 | 24.1 |
|---|------|------|
| B | 23.1 | 24.1 |
| C | 28.2 | 28.8 |
| D | 16.0 | 17.0 |
| E | / | 25 |
| F | 10.8 | 11.2 |
| G | 6.2 | 6.4 |
| H | 0.75 | 0.85 |
| I | 4.5 | 5.5 |



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